

Part Number: XDVG46C

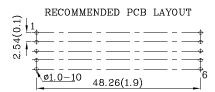
 $44.5 \mathrm{mm}$ (1.75") SINGLE DIGIT NUMERIC DISPLAY

Features

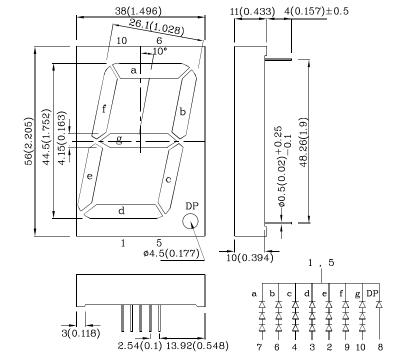
- Low power consumption
- ullet Robust package
- I.C. Compatible
- \bullet Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant







Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	VG (AlGaInP)	Unit		
Reverse Voltage (Per Chip)	V_{R}	5	V	
Forward Current (Dp)	I_{F}	30 (30)	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width (Dp)	i_{FS}	150 (150)	mA	
Power Dissipation (Per Chip)	P_D	75	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)	VG (AlGaInP)	Unit	
Forward Voltage (Typ.) (Dp) (I _F =10mA)	V_{F}	6 (2)	V
Forward Voltage (Max.) (Dp) (I _F =10mA)	V_{F}	7.5 (2.5)	V
Reverse Current (Max.) (Per Chip) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) λP 574* (I _F =10mA)		574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) $\triangle \lambda$ $(I_F=10\text{mA})$		20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd	Wavelength CIE127-2007* nm λP	Description
			min. typ.		
XDVG46C	Green	AlGaInP	52000 139990 21000* 49990*	574*	Common Cathode , Rt.Hand Decimal.

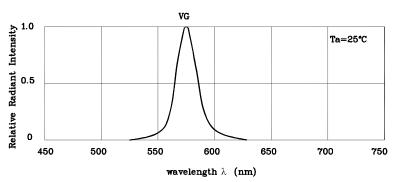
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Mar 10.2014

XDSB7715 V1-X Layout: Maggie L.

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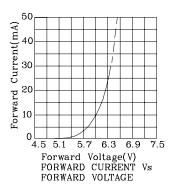
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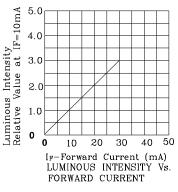


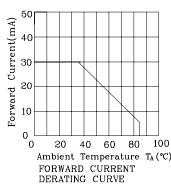


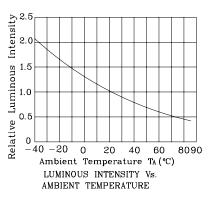
RELATIVE INTENSITY Vs. CIE WAVELENGTH

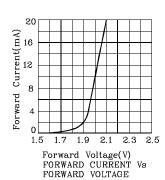
❖ VG

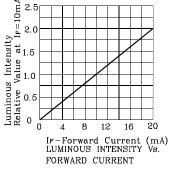


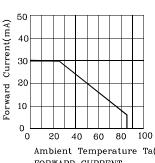


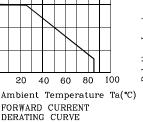


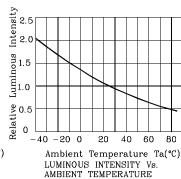




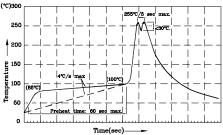








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous Intensity / Luminous Flux: +/-15%

3. Forward Voltage: +/-0.1V

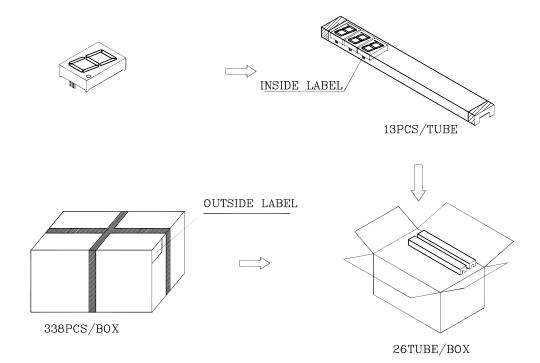
Note: Accuracy may depend on the sorting parameters.

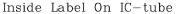
^{2.}Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 s max).
3.Do not apply stress to the epoxy resin while the temperature is above 4.Fixtures should not incur stress on the component when mounting and during soldering process.
5.3AC 305 solder alloy is recommended.
6.No more than one wave soldering pass.
7.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

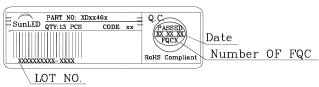
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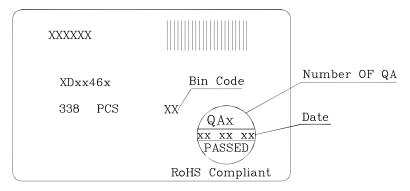
PACKING & LABEL SPECIFICATIONS







Outside Label On Box



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Mar 10,2014